

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	HIRONAO FUJIKI	08/03/2015
RECEIVING PARTY DATA		
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PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14823652	
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DATE SIGNED:	08/12/2015	
Total Attachments: 1		
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ASSIGNMENT

FOR ONE DOLLAR (\$1.00) and other valuable and sufficient consideration, the receipt of which is hereby acknowledged, We

Hironao FUJIKI

being a co-inventor of certain improvements and invention in

CONDUCTIVE COMPOSITION, CONDUCTIVE COMPOSITION PRODUCTION METHOD, ANTI-STATIC RESIN COMPOSITION AND ANTISTATIC RESIN FILM

for which a United States By-Pass Continuation-in-Part Application is to be filed ("United States Patent Application"), which claims priority to International Application No. PCT/JP2014/000752, filed February 14, 2014, which claims priority to Japanese Application No. JP2013-028166, filed February 15, 2013, hereby assign unto

SHIN-ETSU POLYMER CO., LTD.,

an entity organized and existing under the laws of Japan, having a principal place of business at 1-9 Kanda-Sudacho, Chiyoda-ku, Tokyo 1010041, Japan, its successors and assigns, the entire right, title and interest in and to said improvements, inventions and said United States Patent Application, and all divisions, continuations, reissues, and extensions thereof; and to all Letters Patents that may be granted thereon; said improvements, inventions and Letters Patents to be held and enjoyed by said Assignee for its own use and behoove and for the use and behoove of its successors and assigns, to the full end of the term for which said Letters Patents or other rights of protection may be granted, as fully and as entirely as the same would have been held and enjoyed by me had this assignment and sale not been made.

AND I COVENANT, AGREE AND WARRANT that I have a full and unencumbered title to the invention and application hereby assigned, and I further covenant and agree that I will, at any time upon request, without further compensation, execute and deliver any and all papers or instruments that in the opinion of the Assignee may be necessary or desirable to secure said Assignee the full enjoyment of the rights and properties herein conveyed or intended to be conveyed.

IN WITNESS WHEREOF, I have hereunto set my hand and seal:

Date: 2015. 8. 3

Hironao Fujiki
Hironao FUJIKI